

### General Description

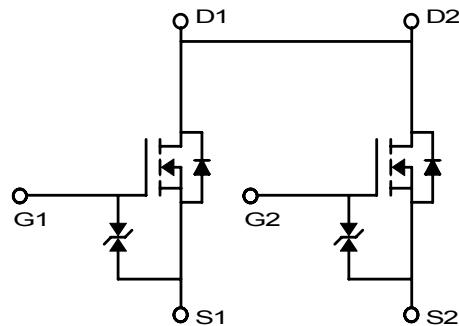
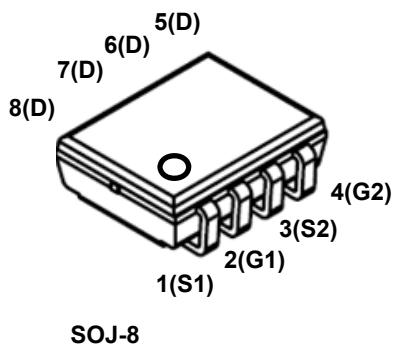
The MDCA0418E uses advanced MagnaChip's MOSFET Technology, which provides low on-state resistance, high switching performance and excellent reliability. Low  $R_{DS(ON)}$  and low gate charge operation with gate voltage as low as 2.5V

### Features

- $V_{DS} = 24V$
- $I_D = 7.0A @ V_{GS} = 10V$
- $R_{DS(ON)}$   
 < 23mΩ @  $V_{GS} = 4.5V$   
 < 24mΩ @  $V_{GS} = 3.9V$   
 < 35mΩ @  $V_{GS} = 2.5V$

### Applications

- Unidirectional or Bi-directional Load Switch
- Lithium-Ion Battery Packs
- Portable Battery Protection Module



### Absolute Maximum Ratings ( $T_a = 25^\circ C$ )

Characteristics	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DSS}$	24	V
Gate-Source Voltage	$V_{GSS}$	$\pm 12$	V
Continuous Drain Current  $T_c=25^\circ C$	$I_D$	7	A
$T_c=70^\circ C$		6	A
Pulsed Drain Current	$I_{DM}$	40	A
Power Dissipation <sup>(1)</sup>  $T_a=25^\circ C$	$P_D$	1.7	W
$T_a=70^\circ C$		1.0	
Junction and Storage Temperature Range	$T_J, T_{stg}$	-55~150	°C

### Thermal Characteristics

Characteristics	Symbol	Rating	Unit
Thermal Resistance, Junction-to-Ambient <sup>(1)</sup>	$R_{\theta JA}$	75	°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	6	

## Ordering Information

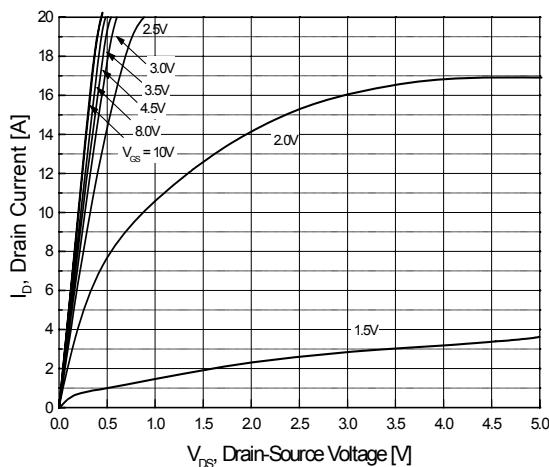
Part Number	Temp. Range	Package	Packing	RoHS Status
MDCA0418EURH	-55~150°C	SOJ-8	Tape & Reel	Halogen Free

## Electrical Characteristics (Ta =25°C)

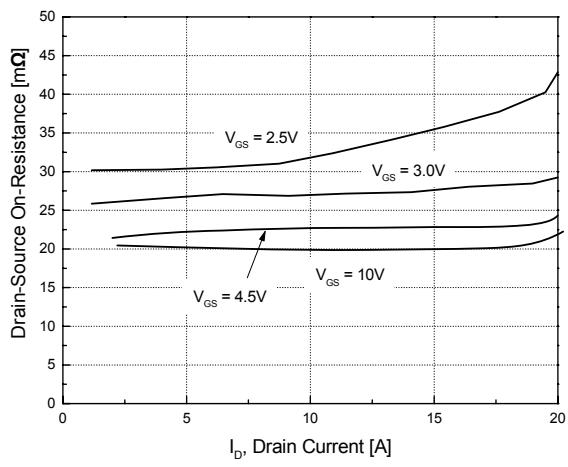
Characteristics	Symbol	Test Condition	Min	Typ	Max	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	I <sub>D</sub> = 250µA, V <sub>GS</sub> = 0V	20	-	-	V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250µA	0.5	-	1.3	
Drain Cut-Off Current	I <sub>DSS</sub>	V <sub>DS</sub> = 20V, V <sub>GS</sub> = 0V	-	-	1	µA
Gate Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±10V, V <sub>DS</sub> = 0V	-	-	10	µA
Drain-Source ON Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 3.0A	-	17	23	mΩ
		V <sub>GS</sub> = 3.9V, I <sub>D</sub> = 3.0A	-	18	24	
		V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 3.0A	-	26	35	
Forward Transconductance	g <sub>fs</sub>	V <sub>DS</sub> = 5V, I <sub>D</sub> = 7A	-	33	-	S
<b>Dynamic Characteristics</b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> = 15V, I <sub>D</sub> = 5A, V <sub>GS</sub> = 4.5V	-	6.2	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	1.2	-	
Gate-Drain Charge	Q <sub>gd</sub>		-	2.5	-	
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0V, f = 1.0MHz	-	501	-	pF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	60	-	
Output Capacitance	C <sub>oss</sub>		-	74	-	
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>GS</sub> = 10V, V <sub>DS</sub> = 15V, R <sub>L</sub> = 1.25Ω, R <sub>G</sub> = 3Ω	-	7	-	ns
Rise Time	t <sub>r</sub>		-	16	-	
Turn-Off Delay Time	t <sub>d(off)</sub>		-	73	-	
Fall Time	t <sub>f</sub>		-	101	-	
<b>Drain-Source Body Diode Characteristics</b>						
Source-Drain Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> = 1A, V <sub>GS</sub> = 0V	-	0.65	1.0	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 11.6A, dI/dt = 100A/µs	-	33	-	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>		-	20	-	nC

Note :

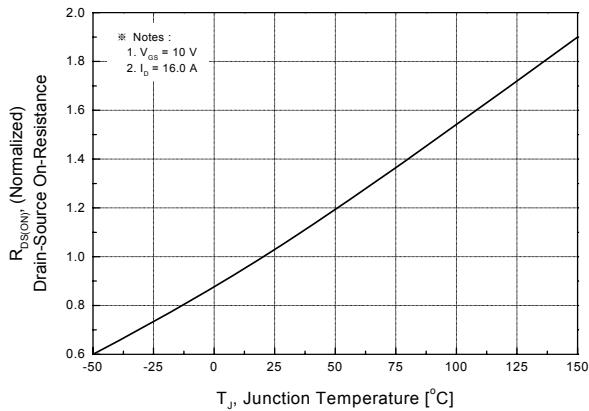
1. Surface mounted FR-4 board with 2oz. Copper.



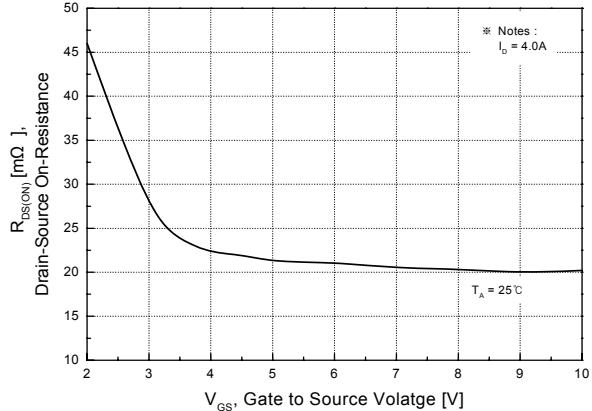
**Fig.1 On-Region Characteristics**



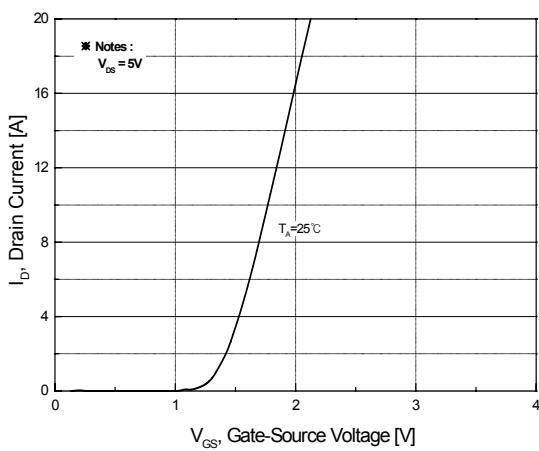
**Fig.2 On-Resistance Variation with Drain Current and Gate Voltage**



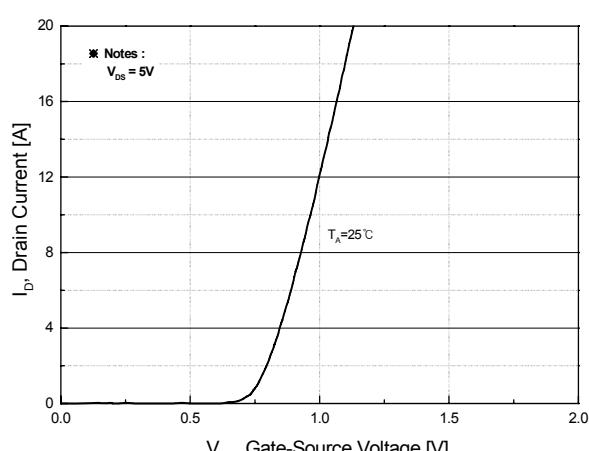
**Fig.3 On-Resistance Variation with Temperature**



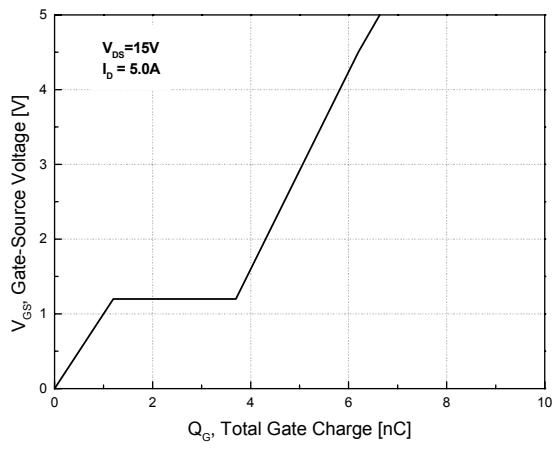
**Fig.4 On-Resistance Variation with Gate to Source Voltage**



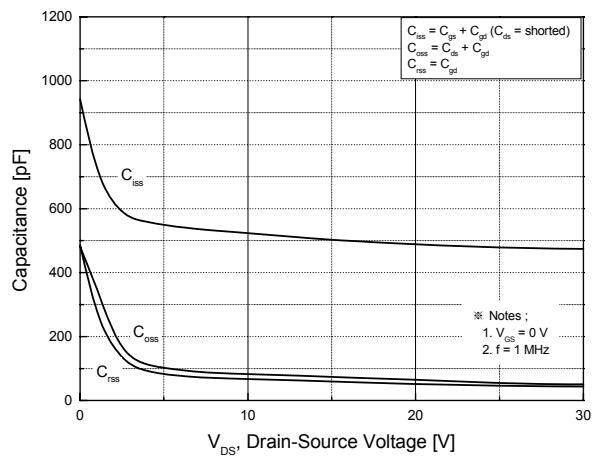
**Fig.5 Transfer Characteristics**



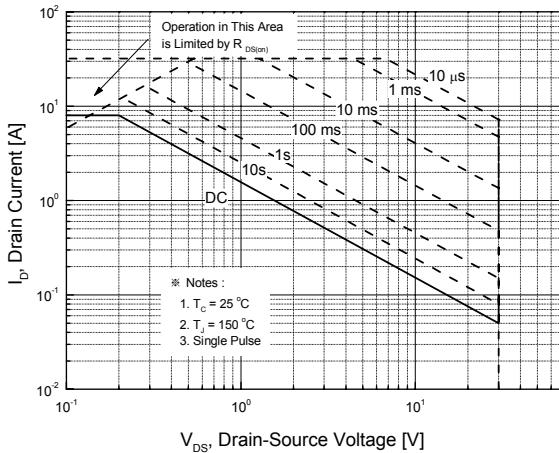
**Fig.6 Body Diode Forward Voltage Variation with Source Current and Temperature**



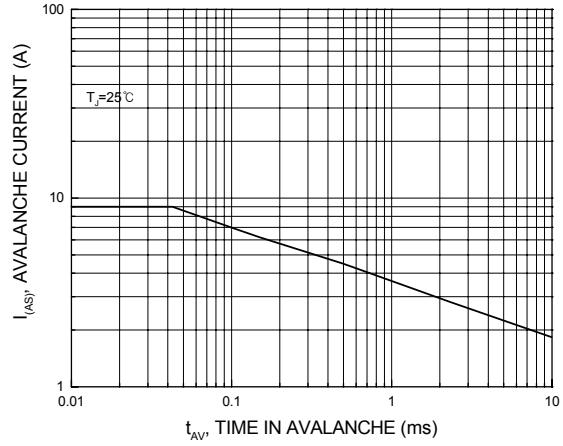
**Fig.7 Gate Charge Characteristics**



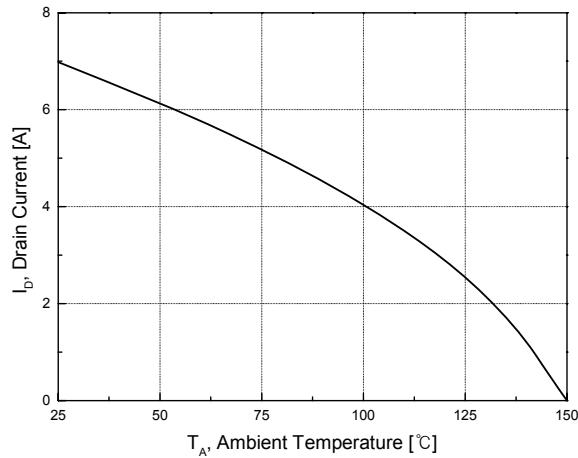
**Fig.8 Capacitance Characteristics**



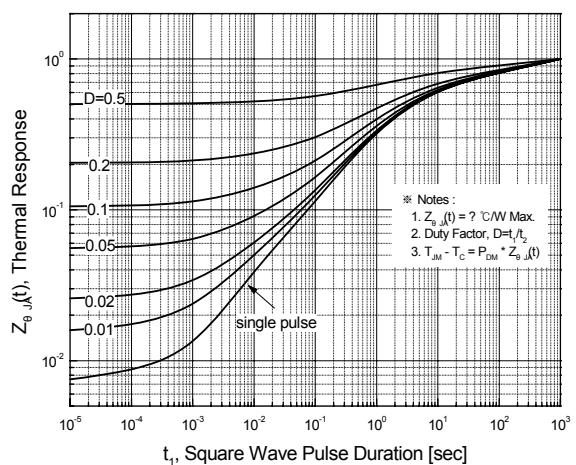
**Fig.9 Maximum Safe Operating Area**



**Fig.10 Unclamped Inductive Switching Capability**



**Fig.11 Maximum Drain Current vs. Case Temperature**

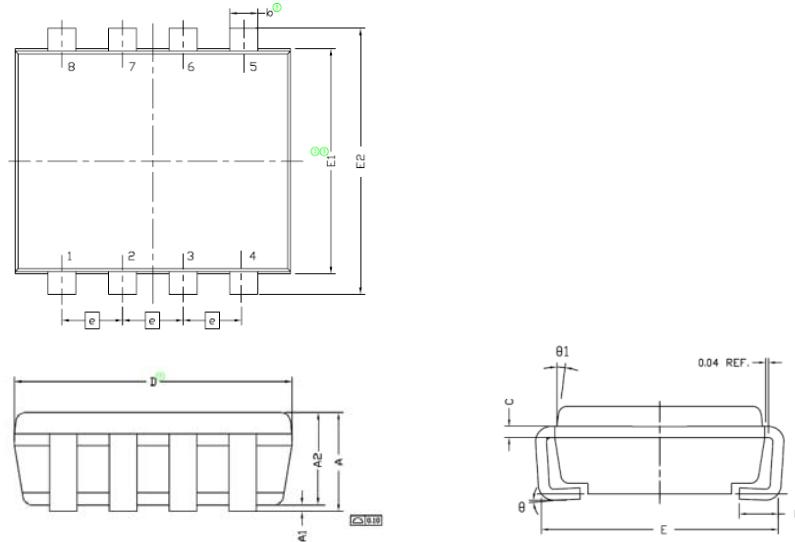


**Fig.12 Transient Thermal Response Curve**

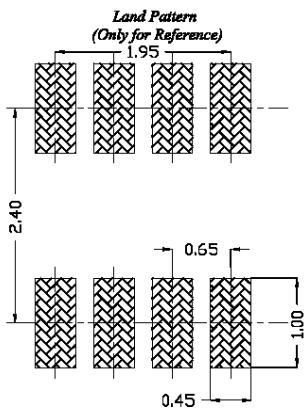
## Physical Dimension

### SOJ, 8 Leads

Dimensions are in millimeters, unless otherwise specified



	SOJ-8		
	Min	Nom	Max
A	-	1.0	-
A1	0.01	-	0.10
A2	0.925	-	1.00
b	0.25	0.32	0.40
c	0.10	0.15	0.20
D	2.95	3.05	3.10
E	2.50	-	3.00
E1	2.30	2.40	2.50
E2	2.65	2.85	3.05
e	0.65BSC		
L	0.30	0.45	0.60
θ	0'	4'	8'
θ1	7' NOM		



**DISCLAIMER:**

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